

## Electronic Patent Application Fee Transmittal

Application Number:	10706977			
Filing Date:	14-Nov-2003			
Title of Invention:	Wafer processing apparatus having dust proof function			
First Named Inventor/Applicant Name:	Tsutomu Okabe			
Filer:	Marvin Jay Spivak/Liping Tan			
Attorney Docket Number:	245166US3CIP			

Filed as Large Entity

### Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
-------------	----------	----------	--------	----------------------

**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

**Extension-of-Time:**

Extension - 1 month with \$0 paid	1251	1	130	130
-----------------------------------	------	---	-----	-----

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>130</b>